



Tecbond 214B

Version: Tecbond 214B-TDS
Date of last issue: 15/7/2025
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General description

Tecbond 214B is a biodegradable packaging adhesive, formulated with 45% bio-based, sustainably sourced raw materials.

The degradation process will occur in the presence of oxygen. When the adhesive is exposed to Ultraviolet light the speed of the degradation process is greatly increased. The adhesive should be kept away from direct sunlight when not in use.

NOTE: Once degradation has begun, it cannot be reversed.

Certifications

Tecbond 214B has been EN13432 certified and tested to ASTM D6400 and D6954 standards.

Substrates*

- Paper
- Cardboard

Technical characteristics

Adhesive type: Synthetic polymer based hotmelt

Colour: Pale amber

Molten tack: High

Bulk Format: Prills

	12mm / ½"	15mm / ⅝"	43mm / 1¾"	Bulk
Carton QTY	5kg / 11lb	5kg / 11lb	10kg / 22lb	20kg/44lb
Suggested application temperature	195°C / 380°F	195°C / 380°F	195°C / 380°F	180°C / 356°F
Brookfield viscosity @180°C (POW-12-VISC) spindle 27	4200cps	4200cps	4200cps	4200cps
Ring & ball softening point (ASTM E28)	104°C / 219°F	104°C / 219°F	104°C / 219°F	104°C / 219°F
Heat resistance (BS5350 Part H3)	75°C / 167°F	75°C / 167°F	75°C / 167°F	75°C / 167°F



Open time	10 secs	10 secs	10 secs	10 secs
Brittle point	0°C / 32°F	0°C / 32°F	0°C / 32°F	0°C / 32°F

Storage

Store in a clean dry place at temperatures between 5°C / 41°F and 25°C / 77°F with boxes closed. Do not expose to direct sunlight or localised heat sources such as radiators or hot pipes. At low temperatures adhesive sticks can become brittle.

Shelf life

Manufacturer guarantees 5-year shelf life after date of manufacture in accordance with suitable storage conditions as mentioned above.

Methods of application

Bead Adhesive Applicator.

Removal of adhesive

Assembled components can be separated by heating assembly to a temperature slightly above the heat resistance figure.

EVA & Polypropylene: Residues of EVA and polypropylene based hotmelts can be removed from components with white spirit.

Polyamide: Residues of polyamide based hotmelt can be removed from components with acetone

Disclaimer

The information contained on this data sheet is for guidance only. It is the result of careful laboratory evaluations by trained and qualified staff using British Standard or similar test methods. However, no warranty is expressed or implied regarding the accuracy of the data or the suitability of the adhesive for any specific purpose. In every case, we strongly recommend that the user shall make their own test to determine to their own satisfaction the suitability of the adhesive for their particular purpose. Neither the seller nor manufacturer shall be liable for any injury, loss, damage, direct or consequential arising out of the use or inability to use the product. Further information is always available to help solve your adhesive problems. Should you require any further information on our adhesives please contact your nearest distributor.

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Technical Data Sheet

F.D.A. approved. All the constituent parts of this adhesive have been approved by the American F.D.A. under C.F.R. 21.175.105 (adhesives) (subject to limitations).